Title:Datasheet for SN6Customer Contact:PCN /		08000	Notificatio	n Da	te: September 19, 20
Customer Contact: PCN/	5HVD104	0A-Q1			
	<u>Manager</u>	Dept:	Quality Ser	vice	S
Change Type:					
Assembly Site		Design			Wafer Bump Site
Assembly Process	\square	Data Sheet			Wafer Bump Material
Assembly Materials		Part number	change		Wafer Bump Process
Mechanical Specification		Test Site			Wafer Fab Site
Packing/Shipping/Labeling		Test Process			Wafer Fab Materials
					Wafer Fab Process
	N	otification	Details		
Description of Change: Fexas Instruments Incorpora					
SN65HVD1040A-Q1					TEXAS INSTRUMENTS
SLLS889C -JUNE 2008-REVISED AUGUST 20	016				www.ti.com
Changes from Revision B (Septemb	per 2011) to F	Revision C			Page
section, Power Supply Recommen Mechanical, Packaging, and Order	ndations section rable Information	on, Layout section, L tion section	evice and Docum	entati	
Mechanical, Packaging, and Order • Changed values in the Thermal Inf	ndations section rable Information formation tabl	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE	evice and Docum	entati	ion Support section, and
Mechanical, Packaging, and Order Changed values in the Thermal Init Fhe datasheet number will b	ndations section rable Information formation tabl	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE	evice and Docum	entati	on Support section, and 1
Mechanical, Packaging, and Order • Changed values in the Thermal Inf	ndations section rable Information formation tabl	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE	evice and Docum	entati	ion Support section, and
Mechanical, Packaging, and Order Changed values in the Thermal Init The datasheet number will b Device Family SN65HVD1040A-Q1 These changes may be revie	ndations section rable Information table of changin exwed at the	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE g. Change Fro SLLS889B e datasheet lin	C standards m: <s provided.<="" td=""><td>entati</td><td>hange To:</td></s>	entati	hange To:
Mechanical, Packaging, and Order Changed values in the Thermal Int The datasheet number will b Device Family SN65HVD1040A-Q1 These changes may be revien http://www.ti.com/lit/ds/syn	ndations section rable Information table of changin exwed at the	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE g. Change Fro SLLS889B e datasheet lin	C standards m: <s provided.<="" td=""><td>entati</td><td>hange To:</td></s>	entati	hange To:
Mechanical, Packaging, and Order Changed values in the Thermal Init The datasheet number will b Device Family SN65HVD1040A-Q1 These changes may be revien http://www.ti.com/lit/ds/syn Reason for Change:	ndations section rable Information formation table one changin ewed at the mlink/sn65	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE g. Change Fro SLLS889B e datasheet lin Shvd1040a-q1.	C standards m: <s provided.<br="">odf</s>	entati	hange To:
Mechanical, Packaging, and Order Changed values in the Thermal Int The datasheet number will b Device Family SN65HVD1040A-Q1 These changes may be revien http://www.ti.com/lit/ds/syn Reason for Change: To more accurately reflect de	evice ther	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE g. Change Fro SLLS889B e datasheet lin Shvd1040a-q1. mal characteris	c standards m: ks provided. odf tics		hange To: LLS889C
Mechanical, Packaging, and Order Changed values in the Thermal Int The datasheet number will b Device Family SN65HVD1040A-Q1 These changes may be revien http://www.ti.com/lit/ds/syn Reason for Change: To more accurately reflect de Anticipated impact on Fit, No anticipated impact. This i	evice ther Form, Form, F	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE G. Change Fro SLLS889B e datasheet lin Shvd1040a-q1. mal characteris unction, Qual	c standards c standards m: cs provided. odf tics tics		hange To: LLS889C
Mechanical, Packaging, and Order Changed values in the Thermal Int The datasheet number will b Device Family SN65HVD1040A-Q1 These changes may be revien http://www.ti.com/lit/ds/syn Reason for Change: To more accurately reflect de Anticipated impact on Fit, No anticipated impact. This is to the actual device	evice ther Form, F orm, F	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE g. Change Fro SLLS889B e datasheet lin Shvd1040a-q1. mal characteris unction, Qual ication change	c standards c standards m: cs provided. <u>odf</u> tics ity or Reliab	Cl Sl	hange To: LLS889C
Mechanical, Packaging, and Order Changed values in the Thermal Int The datasheet number will b Device Family SN65HVD1040A-Q1 These changes may be revien http://www.ti.com/lit/ds/syn Reason for Change: To more accurately reflect de Anticipated impact on Fit, No anticipated impact. This is to the actual device Changes to product identi	evice ther Form, F orm, F	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE g. Change Fro SLLS889B e datasheet lin Shvd1040a-q1. mal characteris unction, Qual ication change	c standards c standards m: cs provided. <u>odf</u> tics ity or Reliab	Cl Sl	hange To: LLS889C
Mechanical, Packaging, and Order • Changed values in the Thermal Ini The datasheet number will b Device Family SN65HVD1040A-Q1 These changes may be revie	evice ther Form, F orm, F	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE g. Change Fro SLLS889B e datasheet lin Shvd1040a-q1. mal characteris unction, Qual ication change	m: c standards m: cs provided. <u>odf</u> tics ity or Reliab	Cl Sl	hange To: LLS889C
Mechanical, Packaging, and Order Changed values in the Thermal Int The datasheet number will b Device Family	ndations section rable Information table of changin exwed at the	on, <i>Layout</i> section, <i>L</i> tion section le to align with JEDE g. Change Fro SLLS889B e datasheet lin	C standards m: <s provided.<="" td=""><td>entati</td><td>hange To:</td></s>	entati	hange To:

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com